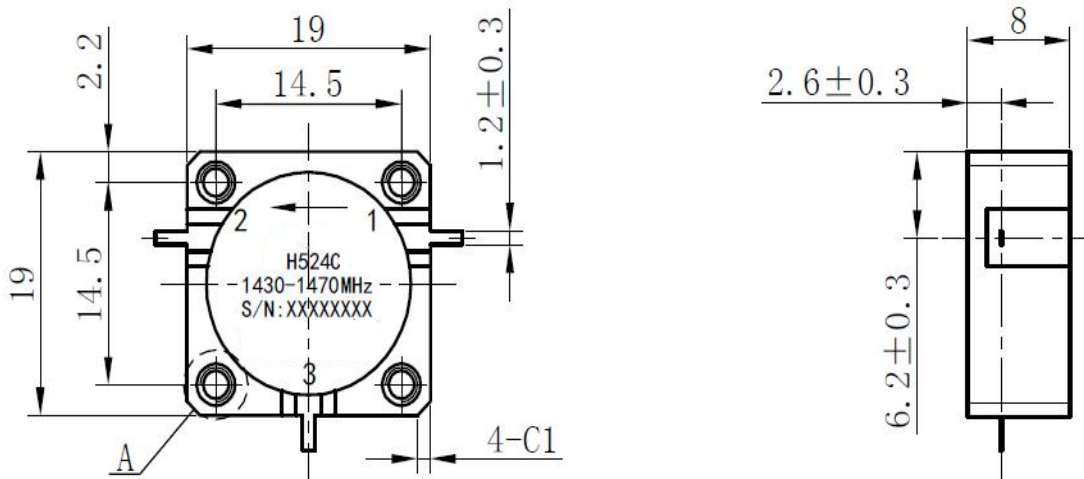


1.Features

- UMTS, LTE Band
- PCB Soldering Re-flow
- Wide Operation Temperature Range -40~ 85°C
- Compact Package Design for PCB Applications

2.Dimensions Unit:mm



3.Specifications

Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H524C[1430-1470]MHz	1.430	1.470	1.4500	0.040	25	0.25	1.15	150	-70
H524C[1805-1920]MHz	1.805	1.920	1.8625	0.115	23	0.28	1.17	150	
H524C[1840-1920]MHz	1.840	1.920	1.8800	0.080	23	0.25	1.17	150	
H524C[2110-2170]MHz	2.110	2.170	2.1400	0.060	23	0.25	1.17	150	
H524C[2300-2400]MHz	2.300	2.400	2.3500	0.100	23	0.25	1.17	150	
H524C[2300-2700]MHz	2.300	2.700	2.500	0.400	20	0.4	1.22	150	
H524C[2555-2655]MHz	2.555	2.655	2.605	0.100	23	0.25	1.17	100	
H524C[2500-2700]MHz	2.500	2.700	2.600	0.200	23	0.25	1.15	100	
H524C[3400-3800]MHz	3.400	3.800	3.600	0.400	23	0.25	2.3	100	
H524C[4100-4400]MHz	4.100	4.400	4.250	0.300	22	0.4	1.2	30	
H524C[4750-5100]MHz	4.750	5.100	4.925	0.350	22	0.35	1.2	10	